## MN-3 August 2011 QE

1. Sketch and identify the physical features of a conventional Si NMOSFET. This is an inversion-type enhancement-mode NMOSFET fabricated on a p-type Si substrate. (15 points)

2. Based on the above structure, considering a submicron NMOSFET with L=0.25  $\mu$ m, Z=5  $\mu$ m, N<sub>A</sub>=10<sup>17</sup>/cm<sup>3</sup>,  $\mu$ <sub>n</sub>=500cm<sup>2</sup>/Vs, C<sub>ox</sub>=3.45x10<sup>-7</sup> F/cm<sup>2</sup>, and V<sub>T</sub>=0.5 V, find the channel conductance for V<sub>G</sub>=1 V and V<sub>D</sub>=0.1V. (20 points)

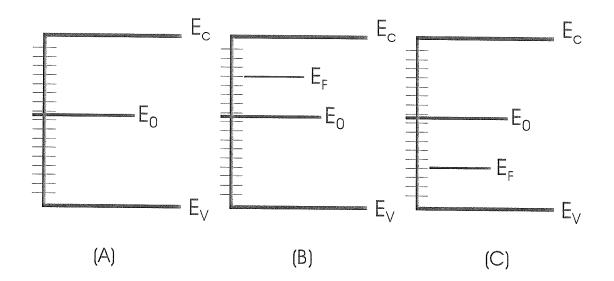
Write in Exam Book Only

3. Sketch and identify the physical features of a depletion-mode Si NMOSFET on a p-type Si substrate, in contrast to Problem 1. How do you distinguish a depletion-mode NMOSFET from an enhancement-mode NMOSFET through electrical characterization? (Hint: Plot the respective transfer characteristics.) (15 points)

4. Assume that the device in Problem 1 and Problem 2 is based on SiO<sub>2</sub>/Si technology. Calculate the equivalent oxide thickness (EOT) of SiO<sub>2</sub> for the device in Problem 2. In order to reduce the gate oxide leakage current, a high-k dielectric is used for advanced Si technology. Envision using a composite high-k structure with the same EOT as the one in Problem 2. The composite structure is assumed to be composed of 1 nm SiO<sub>2</sub> on Si channel, x nm HfO2 (k=20) in the middle, and 1 nm SiO<sub>2</sub> on top next to the metal gate. Calculate the HfO<sub>2</sub> thickness. (10 points)

 $W_{rite\ in\ E_{Xam}\ Book\ Only}$ 

5. A High-k dielectric (HfO<sub>2</sub>) directly on Si leads to a higher interface trap density at the  $HfO_2/Si$  interface compared to the  $SiO_2/Si$  interface. In Sze and Ng's book on Page 214, the trap neutral level  $E_0$  is used to describe a non-ideal oxide-semiconductor interface. Figure A shows that the trap neutral level  $E_0$  locates in between the conduction band minimum and valence band maximum. Identify which part of trap states are dominated by donor-type trap states and which part of trap states are dominated by acceptor-type states in Figure A. If the Fermi level  $E_F$  is located above  $E_0$ , identify which part of traps are filled in Figure B and the sign (+ or – or neutral) of these traps. If the Fermi level  $E_F$  is located below  $E_0$ , identify which part of traps are empty in Figure C and the sign (+ or – or neutral) of these traps. (10 point)



Write in Exam Book Only

6. Sketch the low-frequency and high-frequency C-V characteristics (y-axis C; x-axis V) of an ideal SiO<sub>2</sub>/Si MOS capacitor. What kind of low-frequency and high-frequency C-V curves will be obtained if the measurement is performed on a HfO<sub>2</sub>/Si MOS capacitor with the same EOT but with a significant interface trap density. Please draw all four C-V curves into the same plot. Draw to scale. (10 point)

7. Interface traps affect C-V characteristics and on-state performance of a MOSFET. They also affect the off-state performance of a device. In the presence of a significant interface trap density  $D_{it}$ , the sub-threshold slope becomes S (with  $D_{it}$ )=(In10)(kT/q)(1+C<sub>it</sub>/C<sub>ox</sub>). If the measured value for S is 100 mV/dec, and we assume the device in Problem 4, what is the average  $D_{it}$  for the composite oxide/Si interface? If we cannot improve the interface by means of an optimized process, how could one still achieve a device with S=80 mV/dec? (20 points)

Write in Exam Book Only